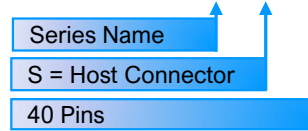


SPECIFICATIONS:

Insulation Resistance: 1,000MΩ min. at 100V DC
 Withstanding Voltage: 300V DC for 1min
 Voltage Rating: 30V DC
 Current Rating: Signal Pin - 0.5A, Power Pin - 1.0A
 Contact Resistance: 20mΩ max. at 20mV max.
 Operating Temp.: -40°C ~ +85°C MAX
 Insertion Force: 40N MAX
 Mating Cycle: 100 times

PART NUMBER:

CNU109S-040-0001



MATERIALS AND FINISH:

- Contacts: Cu Alloy
- Solder Pad: Cu Alloy
- Insulator & Over mold: LCP

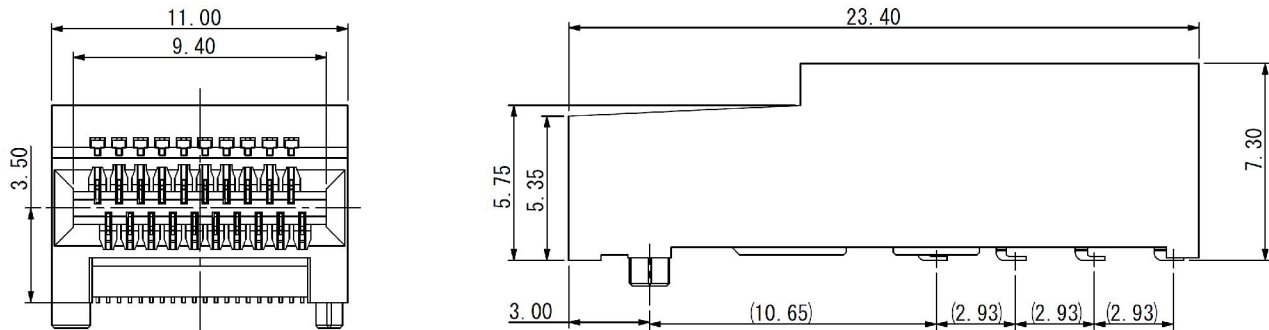
SFP-DD MSA COMPLIANT



FEATURES:

- SFP-DD MSA Design Guideline Compliant
- Supports signals:
 - Supports 25G-NRZ and 56G-PAM4 modulation, providing solutions up to 112G-PAM4
 - Double density with 2 high-speed signal lanes
 - Backward compatibility with current SFP modules

OUTLINE DIMENSIONS:



RECOMMENDED PC BOARD LAYOUT:

